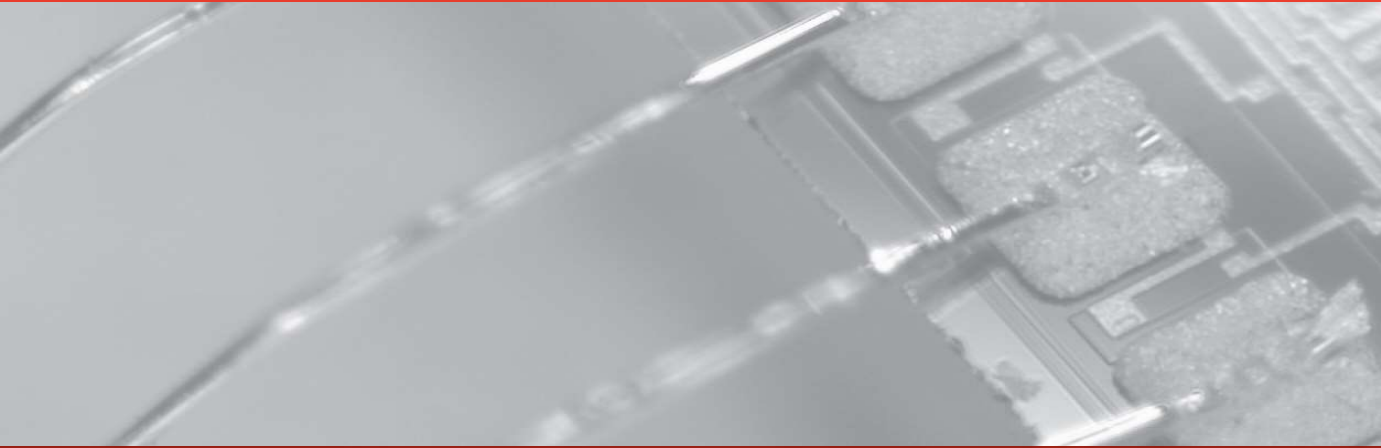


# Services

## Optimum Microelectronics Packaging Solutions



A proven blend of expertise in advanced microelectronics solutions at the R&D and prototype stage.

R&D



Quick-turn  
Prototype



Full-scale  
Production



+ Engineering support from concept to commercialization	+ Ultra fine pitch wire bonding
+ Complex electromechanical system design	+ Au, Al, Cu, Ribbon wire bonding
+ Design for cost, reliability and manufacturability	+ Ball and Wedge wire bonding
+ Proof of concept development and rapid prototyping	+ Flip Chip
+ Design verification, product and process improvements	+ Wafer & Singulated die bumping
+ High level of integration resulting in small form factors	+ Thermosonic & Thermocompression die attach
+ Test, measurement and failure analysis	+ Automatic die attach $\pm 0.5\mu\text{m}$ placement accuracy
+ Supply chain management	+ Underfill and Globtop
+ Materials selection and qualification	+ Epoxy, Solder, Eutectic & Exotic Material die attach
+ Rigorous controls to maintain security of IP	+ SMT Mounting
+ State of the art facilities and equipment	+ Fine pitch BGA attach & Solderball placement
+ Collaborative approach for niche applications	+ Applications in MEMs, VCSEL, Photonics, RFID, etc.

We work at the bare chip level while integrating microelectronics, bioscience or therapeutics to provide highly miniaturized applications. By working in close collaboration with our clients, novel and individual solutions are naturally attained.

We are structured to provide a wide range of design, engineering and manufacturing solutions, offering a technical bridge from R&D through to full scale production.

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